



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

July 29, 2009

Applicant: Chisato HOSHINO

For: THERMAL CONDUCTIVE SILICONE COMPOSITION

Serial No.: 10/567 587 Group: 1796

Confirmation No.: 2543

Filed: August 24, 2006 Examiner: Ojurongbe

International Application No.: PCT/JP2004/014679

International Filing Date: September 29, 2004

Atty. Docket No.: 3400.P1429US

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

Sir:

In response to the Office Action dated April 30, 2009,
please amend the above-identified application as follows:

(Please see following pages.)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service with
sufficient postage as first class mail in an envelope
addressed to: Commissioner for Patents, P.O. Box 1450,
Alexandria, VA 22313-1450, on July 29, 2009.


Terryence F. Chapman